

Glued SAM data sheet SAM- λ -A- τ -4.0-25.0g-c or 4.0-25.0g-e

GaAs chip area standard: 4.0 mm x 4.0 mm
 optional: other dimensions on request

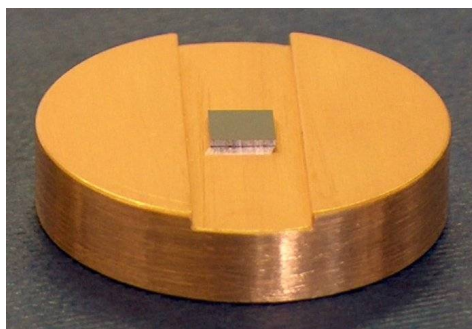
Chip thickness standard: 450 μ m

Front side protection the SAM is protected with a dielectric front layer.

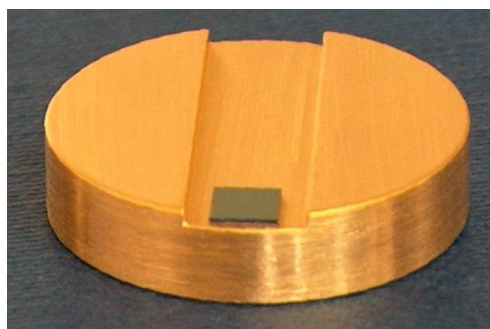
The SAM chip is glued on a gold plated Cu-cylinder with 25.0 mm \varnothing using a thermal conducting glue.

- The **standard** position of the SAM is at the center of the mount \rightarrow x = 4.0-25.0g-c.
- **Optional** the SAM can be mounted at the edge of the mount without extra charges
 \rightarrow x = 4.0-25.0g-e.

Center mounted SAM



Edge mounted SAM



Mount

Cu-cylinder, $\varnothing = 25.0$ mm
l = 6.0 mm

